

Layer	Name	Material	Thickness	Constant	Board Layer	Stack
1	Top Overlay					
2	Top Solder	Solder Bcast	0.012mm	3.5		
3	Top Layer	Copper				
4	Dielectric1	FR4 0.2mm 35/30 copper	0.200mm	4.2		
5	Pre-Layer	Copper				
6	Dielectric2	FR4 0.22mm	0.220mm	4.2		
7	Dielectric 2	Copper				
8	Dielectric3	FR4 0.2mm 35/30 copper	0.200mm	4.2		
9	Signal Layer 1	Copper				
10	Dielectric 4	FR4 0.2mm	0.200mm	4.2		
11	Signal Layer 2	Copper				
12	Dielectric 5	FR4 0.5mm 35/30	0.500mm	4.2		
13	Bottom Layer	Copper				
14	Bottom Solder	Solder Bcast	0.012mm	3.5		
15	Bottom Overlay					

Supplementary Note:
This board is formed creating a 4 layer board and then bonding bottom core and bottom prepreg to the 4 layer board.
This process will create a 5 layer structure with 5 Cu layers and two drill hole pairs.
The top 4 layer board is drilled, plating to 0.5 Oz Cu is required. The bottom core and prepreg are then bonded and drilled. Plated through holes should then be plated to 0.5 Oz Cu (for the drill hole pairs between top and bottom layers). So Silkscreen and chemical finishing should be completed as final processing steps.

NOTES: (UNLESS OTHERWISE SPECIFIED)

1. BOND SPEED - BOND SHALL BE MANUFACTURED TO MEET
ALL SPECS DEFINED UNDER IPC-A-600 LATEST REVISION

2. BMSF INTERSEAL - Fill High Tg ☐ Netal Core ☐ Other ☐ _____
- Tg for LAYDATE AND PRESSURE SHALL BE GREATER THAN OR EQ. TO 175°C

3. COPPER FOOL WEIGHT - SEE TABLE FOR STOCK-UP DETAIL.

Note: board will go through (2) 1up 0.5 Oz plating processes.
Top & Bottom Layers: finished copper weight 35um +plating=60um

4. PLATING ~ 0.5oz ☒ 0.75oz ☐ 1oz ☐ Other ☐

8. FINISH - WMS, Right ☐ WMS, ☐ Decision Solver ☐ ☐

- GREEN ☐ WHITE ☐ BLUE ☐ OTHER ☐ _____

7. GROUNDING - LPE - APPLY EPOXY BASED ZINC

- TOP/BOTTOM ☒ TOP ONLY ☐ BOTTOM ONLY ☐ NO

6. IMPEDANCE CONTROL - NO ☐ YES ☒ SEE TABLE FOR DETAIL.

B. ELECTRICAL TEST - 100% IPC-D-3548

10L ALL PLATED AND NON-PLATED THROUGH HOLES ARE TO BE DRILLED AT PAIRW

^a ALL WALK LOCATION TOLERANCES ARE TO BE ± 0.002 IN REPE.[illegible]

IN THE DRILL LEGEND

14. REEXISTATION - REEXISTATION OF PATTERNS TO BE ACTION +/- .006 LOCATION C
TO DIMENSION SHOWN

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		Date 19/04/2002